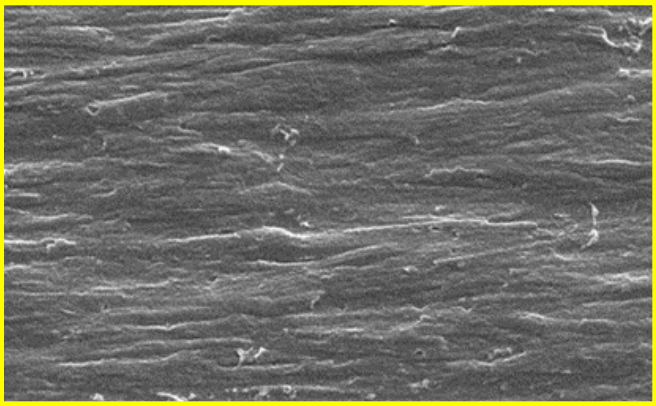
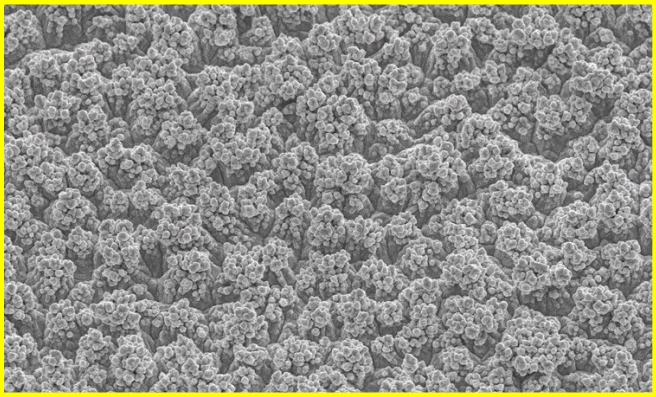
Co-Tech
DEVELOPMENT CORP.
The First Choice Of Copper Foil Provider

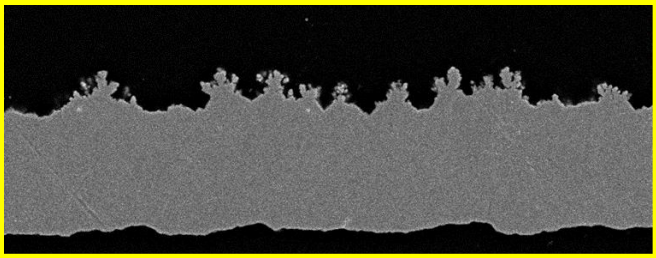
FC310



18μm Untreated-side Foil SEM × 1500



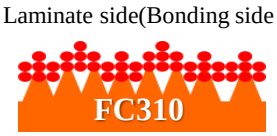
18μm Treated-side Foil SEM × 1500



18μm Foil Cross Section SEM × 1500

Composition :

– Cross Section :



– Resist/ Bonding Side Color : Pink/ Pink

Application:

– HSD (High speed digital)
– 3L-FCCL
– Material: Typical substrates include polyimide and bismaleimide triazine (BT) epoxy blends, cyanate esters, polyimide and thermoplastics.

Feature:

– FC310 foil with very low profile to have excellent insulation result and good etch ability, and lower electrical resistivity compared to regular ED foils.
– Low profile of FC310 makes it an excellent material to apply 3L-FCCL.
– Excellent anti-oxidation and shelf life.

Type	FC310		Thickness	Physical Properties						Roughness JIS94 (μm)	
				Area Wt.	Tensile(kg/mm^2)		Elongation(%)		Peel Strength FR4*1		
	(oz)	(μm)	(μm)	(g/m^2)	RT	180℃	RT	180℃	(lb/inch)	kg/cm	Ra(s/s)	Rz(m/s)
FC310 (Pink Color)	Toz	12μ	12±2.0	105±5	≧33	≧17	≧3	≧3	≧5.0	≧0.89	≦0.40	≦4.5
	Hoz	18μ	18±2.0	150±8	≧33	≧17	≧5	≧3	≧6.5	≧1.16	≦0.40	≦5.5
	1oz	35μ	33±3.5	280±10	≧30	≧17	≧10	≧5	≧8.5	≧1.52	≦0.40	≦8.0

※ FR4 *1 : Tg≒140℃ ※This is representative data, not guarantee.